2SD2249

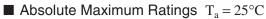
Silicon NPN epitaxial planar type

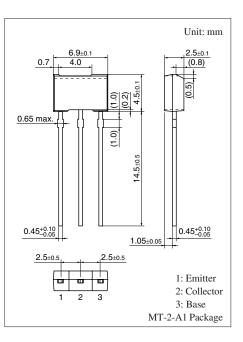
For low-frequency power amplification

Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- Satisfactory operation performances at high efficiency with the low-voltage power supply.
- Allowing supply with the radial taping

Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	40	V			
Collector-emitter voltage (Base open)	V _{CEO}	20	V			
Emitter-base voltage (Collector open)	V _{EBO}	7	V			
Collector current	I _C	5	А			
Peak collector current	I _{CP}	8	А			
Collector power dissipation *	P _C	1	W			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			





Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

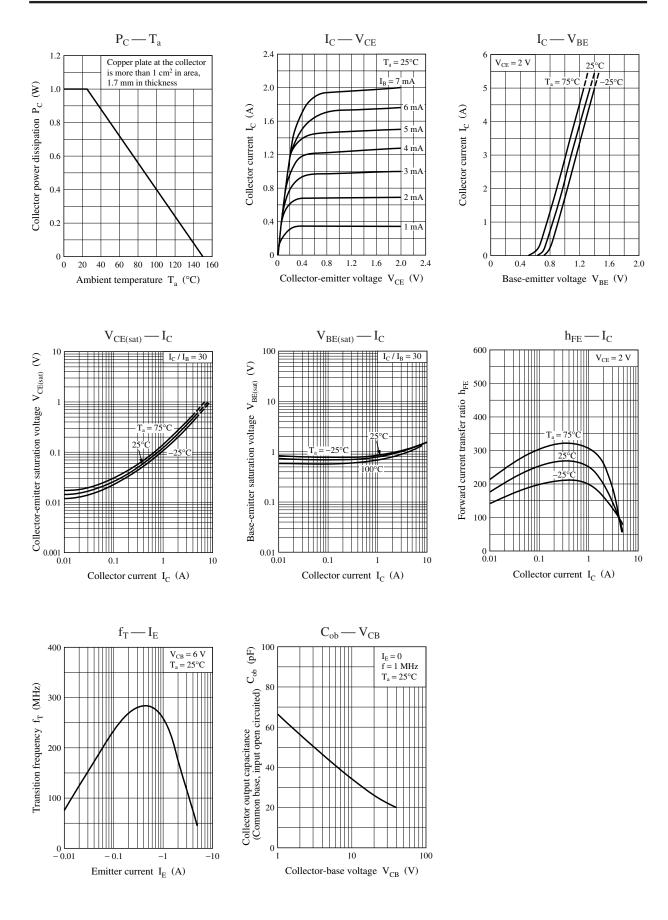
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$	20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			0.1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 2 V, I_C = 0.5 A$	230		600	
	h _{FE2}	$V_{CE} = 2 V, I_C = 2 A$	150			
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{\rm C} = 3 \text{ A}, I_{\rm B} = 0.1 \text{ A}$		0.3	1.0	V
Transition frequency *1	f _T	$V_{CB} = 6 V, I_E = -50 mA, f = 200 MHz$		150		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			50	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *1: Pulse measurement

*2: Rank classification

Rank	R	S
h _{FE1}	230 to 380	340 to 600

Panasonic



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